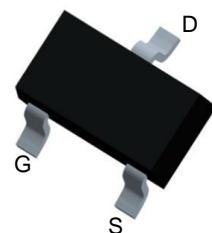
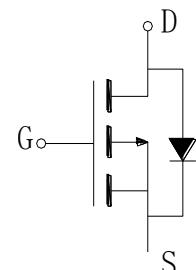


## Features

- -40V/-5A,  
 $R_{DS(ON)} = 30m\Omega$ (Typ.)@ $V_{GS}=-10V$   
 $R_{DS(ON)} = 40m\Omega$ (Typ.)@ $V_{GS}=-4.5V$
- Low  $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and Rugged


**SOT23-3L**


## Applications

- Load Switch

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b> ( $T_A=25^\circ C$ Unless Otherwise Noted)			
$V_{DSS}$	Drain-Source Voltage	-40	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$T_J$	Maximum Junction Temperature	150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$I_S$	Diode Continuous Forward Current	$T_A=25^\circ C$	-1.2
			A
<b>Mounted on Large Heat Sink</b>			
$I_{DP}^{①}$	300 $\mu$ s Pulse Drain Current Tested	$T_A=25^\circ C$	-20
$I_D^{②}$	Continuous Drain Current( $V_{GS}=-10V$ )	$T_A=25^\circ C$	-5
		$T_A=70^\circ C$	-4
$P_D$	Maximum Power Dissipation	$T_A=25^\circ C$	1.25
		$T_A=70^\circ C$	0.8
$R_{\theta JC}$	Thermal Resistance-Junction to Case	-	$^\circ C/W$
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	100	$^\circ C/W$
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}^{④}$	Avalanche Energy, Single Pulsed	TBD	mJ

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Test Condition	CM4207P			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{DS}}=-250\mu\text{A}$	-40			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-40\text{V}, V_{\text{GS}}=0\text{V}$			-1	$\mu\text{A}$
		$T_J=125^\circ\text{C}$			-100	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{DS}}=-250\mu\text{A}$	-1.1	-1.6	-2.3	V
$I_{\text{GSS}}$	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
$R_{\text{DS}(\text{ON})}^{(5)}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{DS}}=-4\text{A}$		30	35	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{DS}}=-3\text{A}$		40	50	$\text{m}\Omega$
<b>Diode Characteristics</b>						
$V_{\text{SD}}^{(5)}$	Diode Forward Voltage	$I_{\text{SD}}=-4\text{A}, V_{\text{GS}}=0\text{V}$		-0.85	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_{\text{SD}}=-4\text{A}, dI_{\text{SD}}/dt=-100\text{A}/\mu\text{s}$		39		ns
$Q_{\text{rr}}$	Reverse Recovery Charge			22		nC
<b>Dynamic Characteristics</b> <sup>(6)</sup>						
$R_G$	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$		6		$\Omega$
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-20\text{V}, \text{Frequency}=1.0\text{MHz}$		1415		$\text{pF}$
$C_{\text{oss}}$	Output Capacitance			130		
$C_{\text{rss}}$	Reverse Transfer Capacitance			100		
$t_{\text{d}(\text{ON})}$	Turn-on Delay Time	$V_{\text{DD}}=-20\text{V}, I_{\text{DS}}=-4\text{A}, V_{\text{GEN}}=-10\text{V}, R_G=3\Omega$		8		ns
$t_r$	Turn-on Rise Time			13		
$t_{\text{d}(\text{OFF})}$	Turn-off Delay Time			30		
$t_f$	Turn-off Fall Time			12		
<b>Gate Charge Characteristics</b> <sup>(6)</sup>						
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=-10\text{V}, I_{\text{DS}}=-4\text{A}$		11		nC
$Q_{\text{gs}}$	Gate-Source Charge			3.7		
$Q_{\text{gd}}$	Gate-Drain Charge			3.2		

Notes:    ①Pulse width limited by safe operating area.

②Calculated continuous current based on maximum allowable junction temperature.

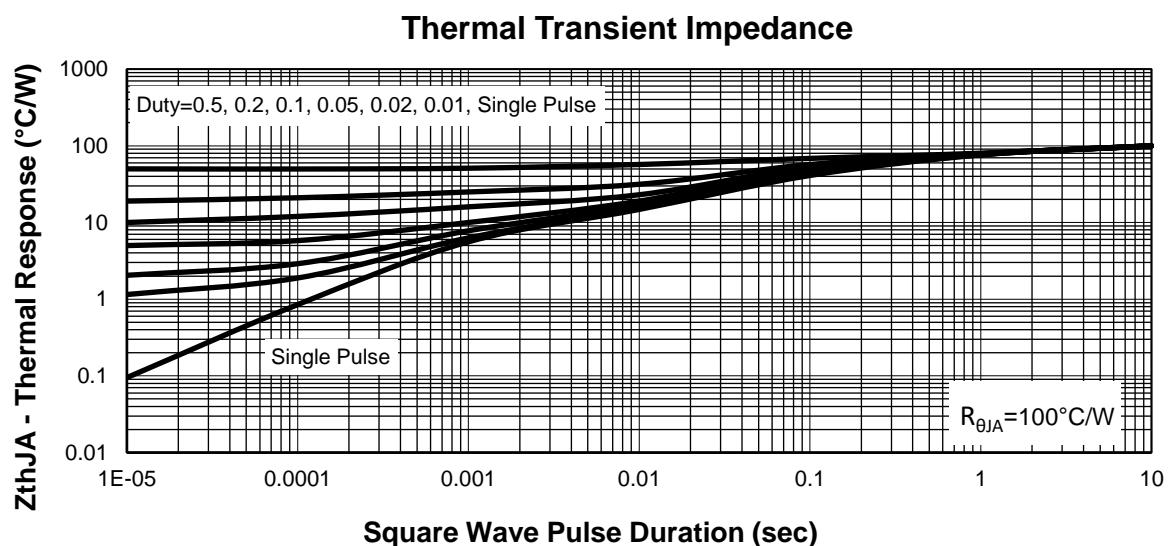
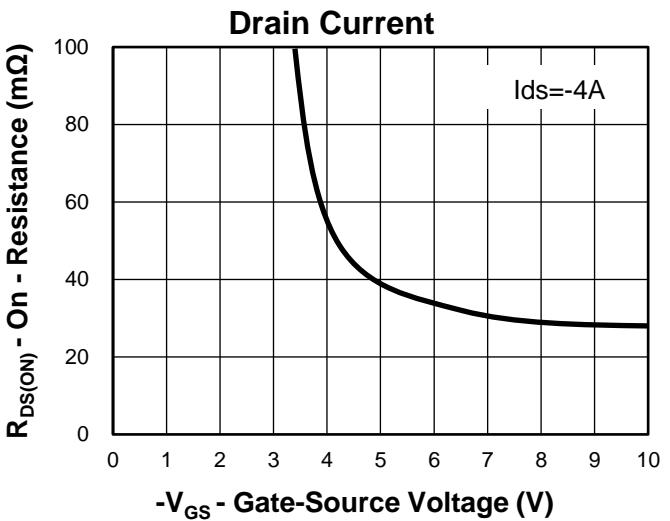
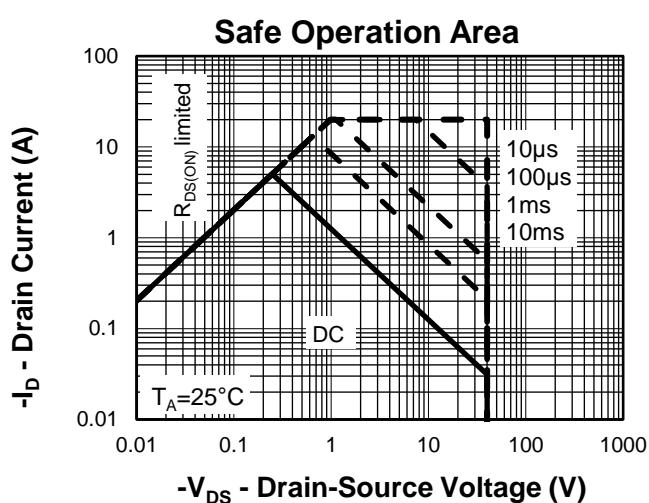
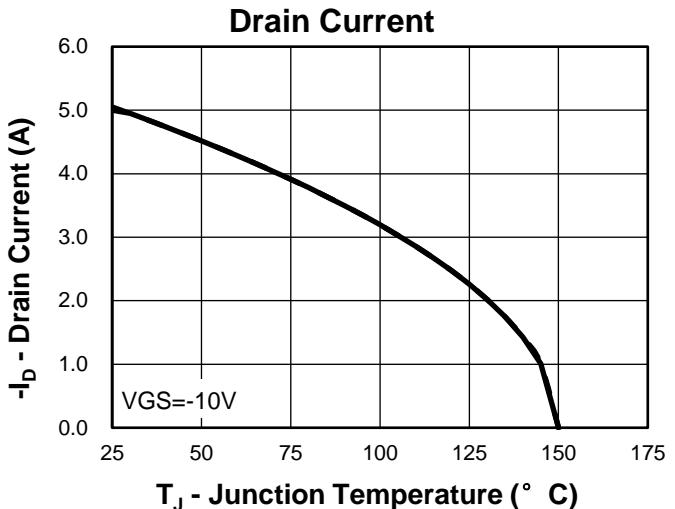
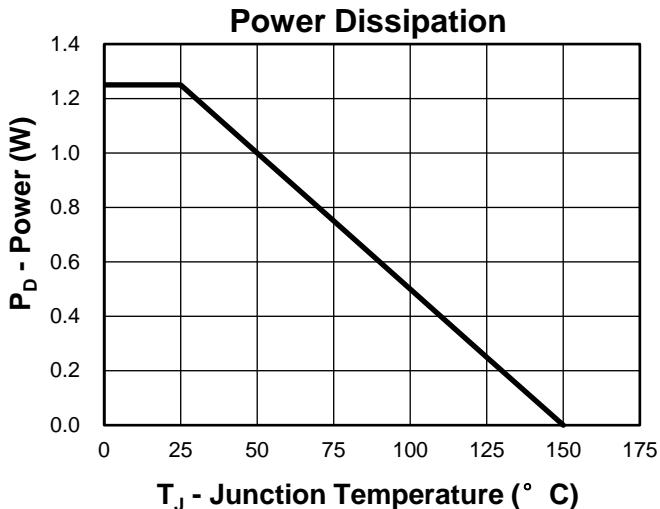
③When mounted on 1 inch square copper board,  $t \leq 10\text{sec}$ . The value in any given application depends on the user's specific board design.

④Limited by  $T_{J\max}$ , Starting  $T_J = 25^\circ\text{C}$ .

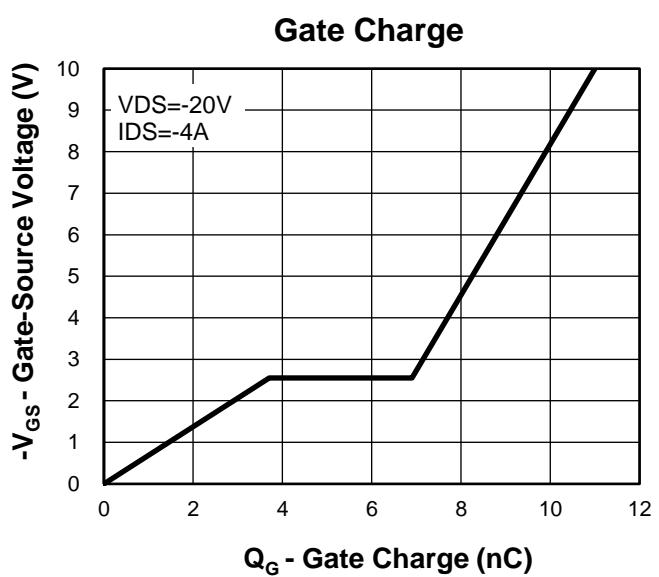
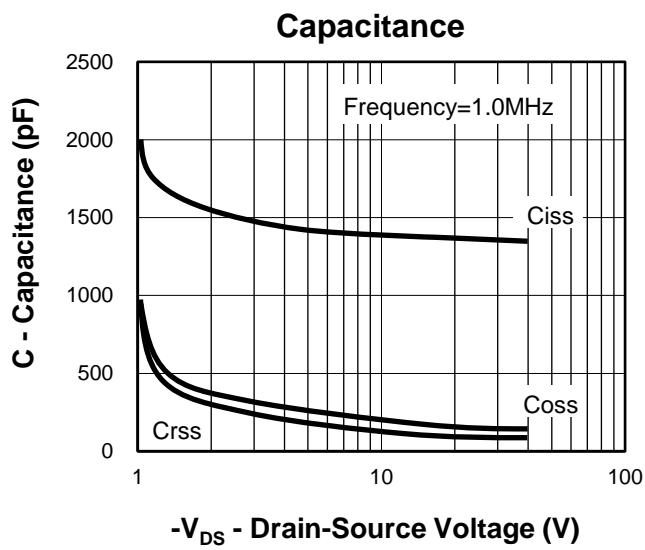
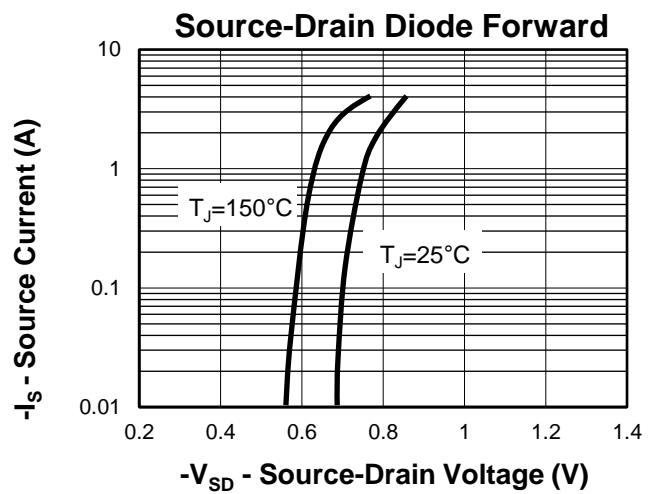
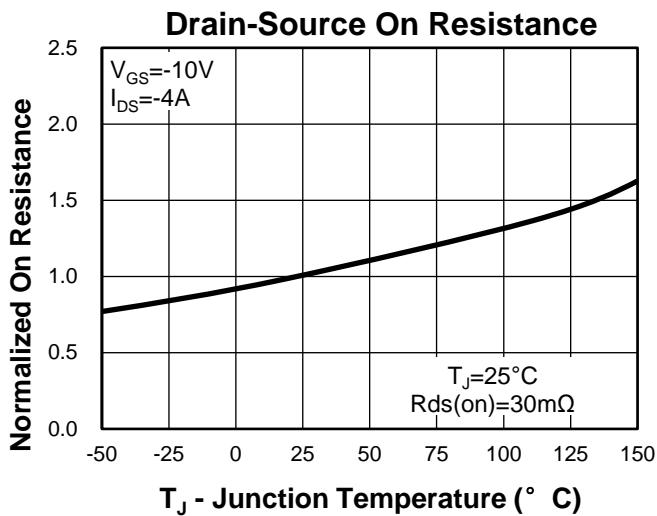
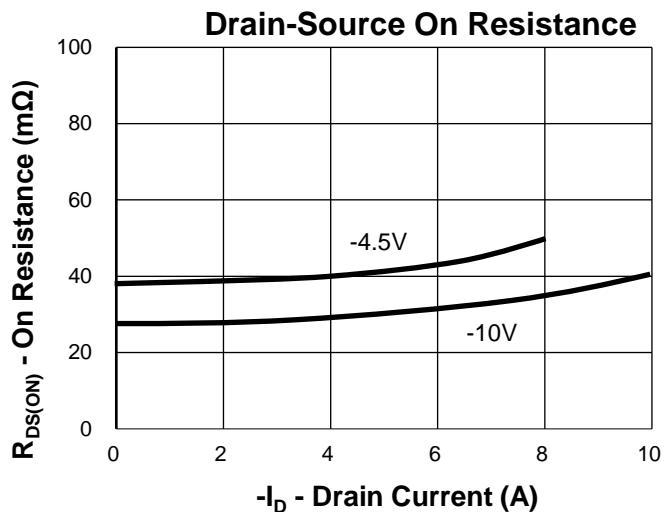
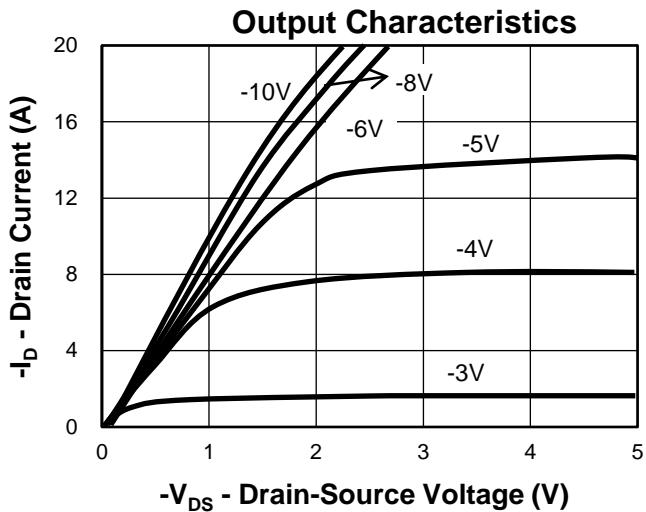
⑤Pulse test; Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .

⑥Guaranteed by design, not subject to production testing.

## Typical Characteristics

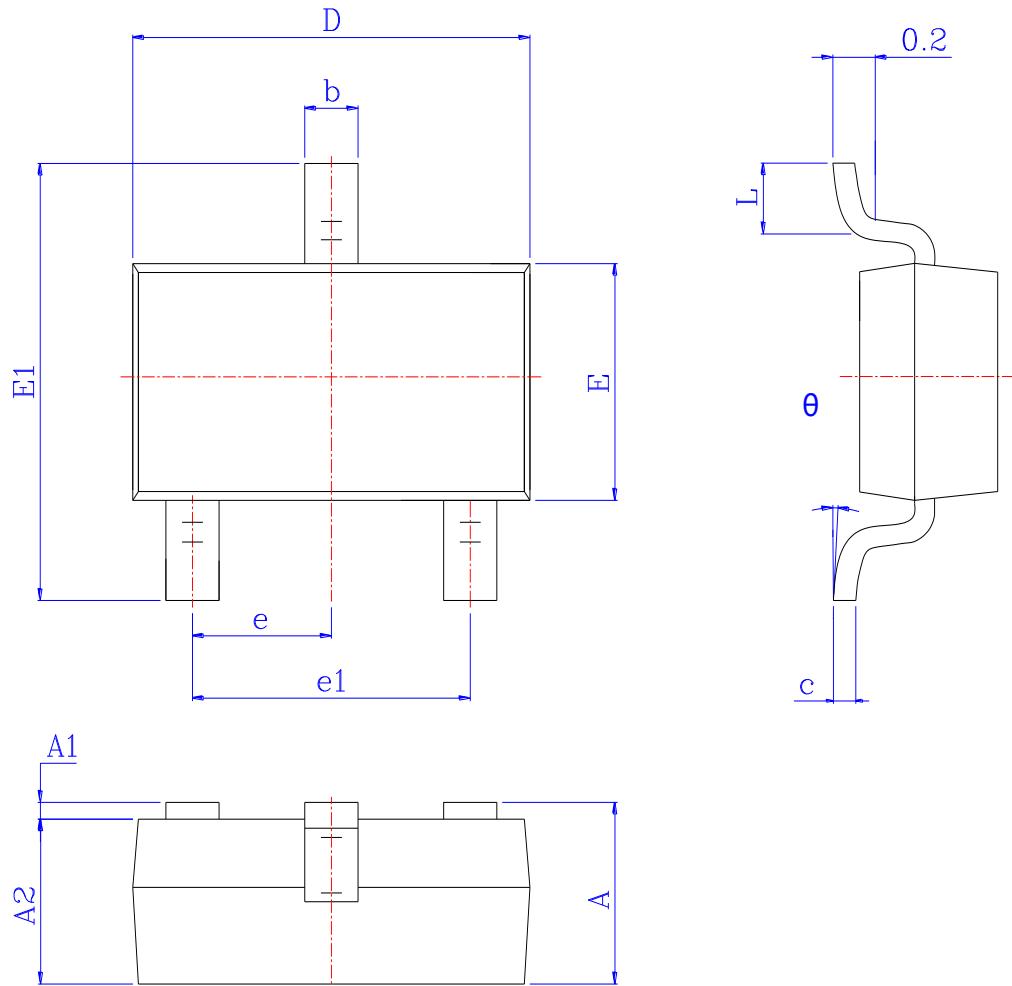


## Typical Characteristics



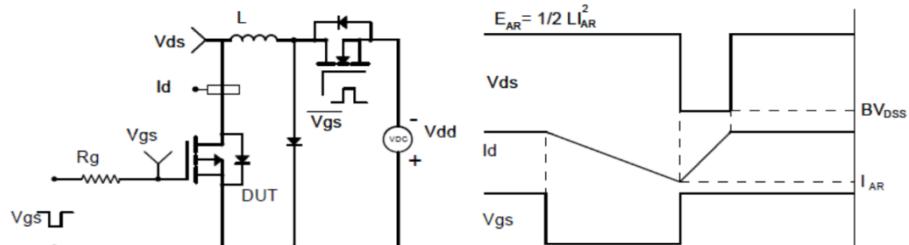
## Package Information

**SOT23-3L**

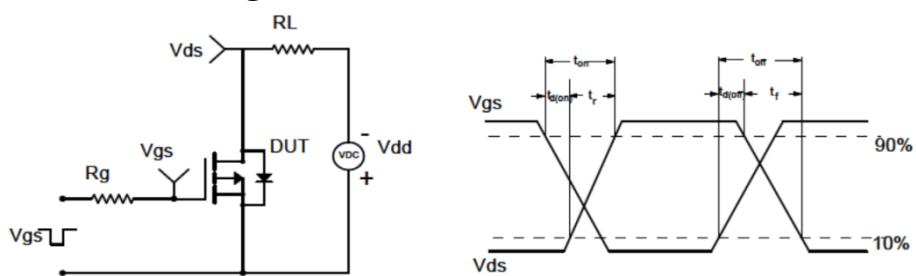


SYMBOL	MIN			MAX		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.950	1.150	1.450	0.037	0.045	0.057
A1	0.000	*	0.150	0.000	*	0.006
A2	0.900	1.100	1.300	0.035	0.043	0.051
b	0.300	0.400	0.500	0.012	0.016	0.020
c	0.080	0.150	0.200	0.003	0.006	0.008
D	2.800	2.925	3.050	0.110	0.115	0.120
E	1.500	1.600	1.750	0.059	0.063	0.069
E1	2.650	2.800	3.000	0.104	0.110	0.118
e	0.950 BSC			0.037 BSC		
e1	1.800	1.900	2.000	0.071	0.075	0.079
L	0.300	0.450	0.600	0.012	0.018	0.024
θ	0°	4°	8°	0°	4°	8°

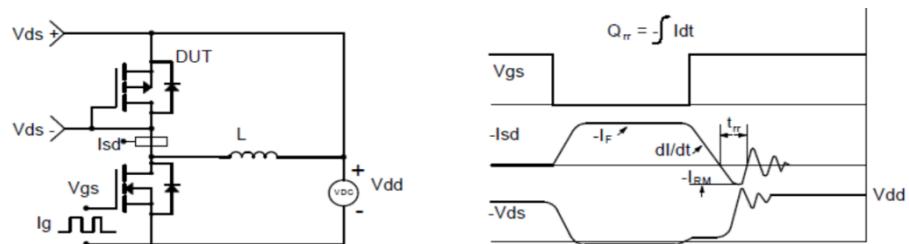
### Avalanche Test Circuit and Waveforms



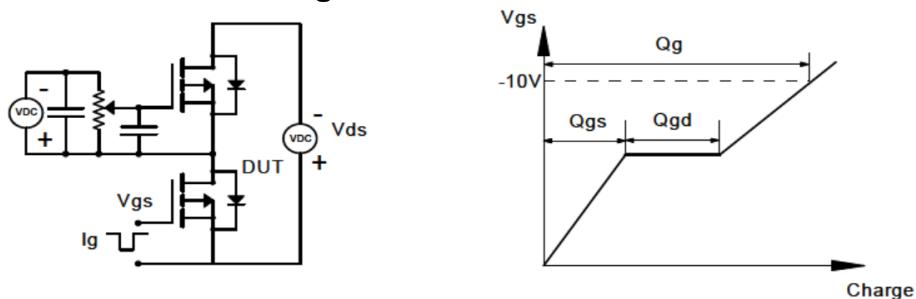
### Switching Time Test Circuit and Waveforms



### Diode Recovery Test Circuit and Waveforms



### Gate Charge Test Circuit and Waveform



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